

SQS24LF BOM-style material declaration. BI Technologies Corporation

9/23/2010

No content here is banned per E.U. R.o.H.S.. Average mass of SQS24LF thin film network is 0.1 grams each. Prepared by Eric Arnold (714) 447-2565
Weights in table above 1 milligram rounded to the nearest mg. Values less than 1 milligram given in scientific notation.

Sub-component	Material	% of total mass	Substance name	CAS #	Substance Weight (grams)	Special classification
Die	substrate	6.7%	Si	7440-21-3	0.008	
		0.02%	SiO2, amorphous	7631-86-9	2.52E-05	
	nichrome resistor	0.0001%	NiCrOx	combination of 7440-02-0, 7440-47-3, & 1308-38-9	1.61E-07	
		0.0002%	TiW	combination of 7440-02-0 & 7440-33-7	2.30E-07	
		0.005%	Au	7440-57-5	5.44E-06	
		0.004%	dvs-BCB, divinylsiloxane-bis-benzocyclobutene	124221-30-3	5.16E-06	
Leadframe	copper alloy	34.7%	Cu	7440-50-8	0.041	
			Fe	7439-89-6	9.79E-04	
			P	7723-14-0	1.25E-05	
			Zn	7440-66-6	5.00E-05	
			Sn	7440-31-5	0.002	
			Ag	7440-22-4	0.001	
Die adhesive	conductive epoxy	0.9%	Ag	7440-22-4	8.40E-04	
			trade secret	unknown	2.10E-04	non-hazardous
Wire bonds	gold	0.04%	Au	7440-57-5	5.44E-06	
Molding compound	filled epoxy	55.3%	carbon black	1333-86-4	3.32E-04	
			epoxy resin, cresol novolac	29690-82-2	0.001	
			SiO2, fused silica	60676-86-0	0.058	
			trade secret	unknown	0.007	non-hazardous
			trade secret	unknown	4.95E-05	non-hazardous
Ink marking	epoxy	0.04%	trade secret	unknown	4.95E-05	non-hazardous